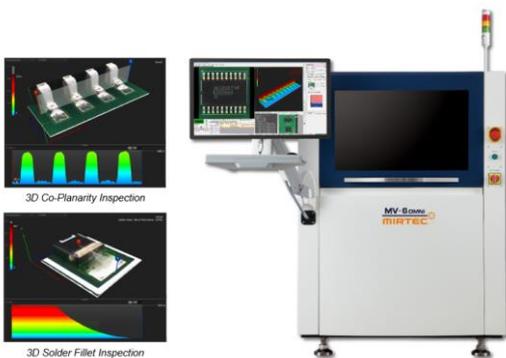




**FOR IMMEDIATE RELEASE**

## **Hot Off Record Breaking Q1, MIRTEC Europe to Exhibit at SMT/Hybrid/Packaging**

**April 2016** – MIRTEC, “The Global Leader in Inspection Technology,” announced that MIRTEC Europe had a record breaking first quarter and has high expectations for the months to come. Also, MIRTEC will display its award-winning 3D AOI and SPI Inspection Systems in pc tec’s booth, Hall 7A, Stand 504, at the upcoming SMT/Hybrid/Packaging show, scheduled to take place April 26-28, 2016 at the Messe in Nuremberg, Germany.



MIRTEC will exhibit the award-winning **MV-6 OMNI 3D AOI Machine** which is configured with MIRTEC’s exclusive OMNI-VISION® 3D Inspection Technology which combines our 15 Mega Pixel CoaXPress Camera Technology with MIRTEC’s revolutionary Digital Multi-Frequency Quad Moiré 3D system and 8 Phase colour lighting in a newly designed cost effective platform (**Full 3D for less than \$100K**).

MIRTEC’s 15 Mega Pixel CoaXPress Vision System is a proprietary camera system designed and manufactured by MIRTEC for use with our complete product range of 3D inspection systems. MIRTEC’s Digital Multi-Frequency Quad Moiré Technology, provides true 3D inspection using a total of four (4) Programmable Digital Moiré Projectors to yield precise height measurement data used to detect lifted component and lifted lead defects as well as solder volume post reflow. Fully configured the new MIRTEC MV-6 OMNI machines feature four (4) 10 Mega Pixel (Side-Viewer®) Cameras in addition to the 15 Mega Pixel Top-Down Camera. There is little doubt that this technology has set the standard by which all other inspection equipment is measured.

MIRTEC’s flagship, the **MV-9** AOI system, achieves the highest productivity and ultimate inspection performance, For the 3D measurement the MV-9 system has an unrivaled +/-2um repeatability and "Shadow Free" Moiré Phase Shift image processing. Additionally, it is equipped with the 8 Phase colour lighting system. The **MV-9** utilizes a high resolution digital 15 MP camera technology with telecentric lens. The four 10 Mega Pixel (Side-Viewer®) cameras offer a spacial test and provide valuable information for a secure and reliable detection of side defects. Also, the inspection of complex components is greatly enhanced. The MV-9 is now also available with a 25 MP camera and 7.7 µm lens for components down to 03015.

Also on display will be the **MS-15** In-Line SPI System with the latest 15meg camera. It also uses the shadow free Moiré Phase Shift Imaging technology to inspect solder paste depositions on PCBs post screen print for insufficient or excessive solder, shape deformity, shift of deposition and bridging. The MS-15 uses the same high precision platform as MIRTEC’s MV-9 Series.

All MIRTEC 3D systems are equipped with the high speed data transfer CoaXPress technology which leads to an increase of inspection speed of around 25% compared to the standard camera technologies. CoaXPress combines the simplicity of coaxial cable with state of the art high speed serial data technology. The combination of these two features provides a revolutionary leap forward in high speed image and data transmission. The systems can also be configured with MIRTEC’s exclusive Quantum High Definition (2048x1536) Digital Multi-Frequency 3D Projection

Technology to provide unprecedented image quality, accuracy and repeatability necessary for precision inspection of SMT devices on finished PCB assemblies.

MIRTEC's total quality management system software, **INTELLISYS**<sup>®</sup> also will be on display at the IPC APEX EXPO. This software suite promotes continuous process improvement by allowing manufacturers to track and eliminate defects on inspected assemblies.

MIRTEC's **MV-7 3D AOI Machine** features the next generation of MIRTEC's award-winning OMNI-VISION<sup>®</sup> 3D Inspection Technology in a High-Performance AC Servo Drive Platform. This revolutionary technology combines our proprietary 15MP CoaXPress Vision System with The MV-7 OMNI-QHD machine also features four (4) 10 Mega Pixel Side-View Cameras for inspection of Regions of Interest which are not accessible with the 15 MP Top-Down Camera. The **MV-7 OMNI-QHD 3D AOI Machine** will also be on display in the Yxlon booth (7A, 304) linked to the Cheetah and showing the award winning **SmartLoop** link between 3D AOI and X-ray in action.



For more information, stop by booth #7A-504 at the show, or visit [www.mirtec.com](http://www.mirtec.com) or [www.pbtecsolutions.com](http://www.pbtecsolutions.com).

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